

Photodiode array chip FM037P

Description

FM037P chip is fabricated using Silicon Bipolar process technology. The chip is designed to be used in MOS-relay. It includes short-current protection circuit.

New monolith polysilicon structure.

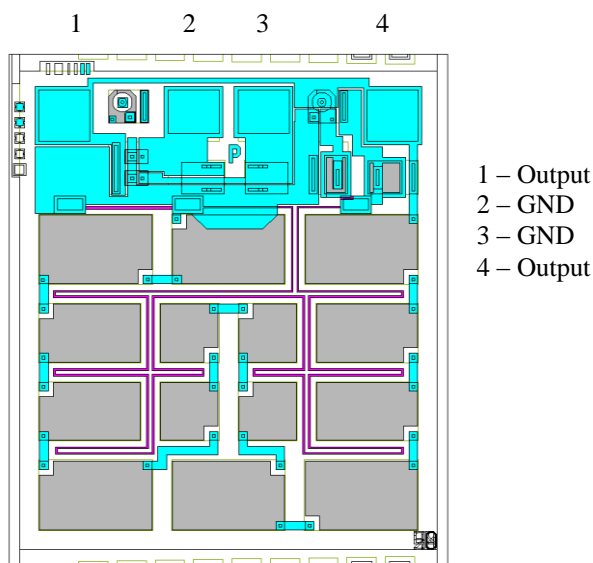
No delamination at high temperatures.

Features

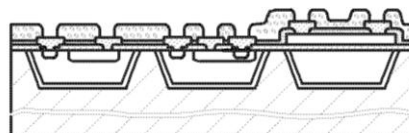
- 14 photodiodes
- Thyristor discharge circuit
- Contact pad's material - Aluminium
- Chip size $1.2 \times 1.4 \pm 0.1$ mm
- Chip thickness 0.32 ± 0.02 mm

Absolute maximum ratings

Storage temperature	- 65 °C to 150 °C
Operating junction temperature	- 55 °C to 125 °C



Cross section view



Electrical characteristics (T = 25 °C)

Parameter	Symbol	Unit	Min	Typ	Max	Condition
Open Circuit Voltage	V _{OC}	V	7.0	8.0	-	1
Short Circuit Current	I _{SC}	μA	3.1	3.4	-	1
Output Voltage	V _{OUT}	V	-	-	0.9	2
Current Limit	I _{LMT}	mA	100	180	240	1
Discharge Resistor	R _{DIS}	MOhm	5.0	-	25.0	
Turn-On Time	T _{ON}	ms	-	0.2	-	C _L = 250 pF
Turn-Off Time	T _{OFF}	ms	-	0.1	-	C _L = 250 pF

- 1 – Light source with peak wavelength $\lambda = 850 \pm 20$ nm that provides surface irradiance $E_e = 20$ mWt/cm²
 2 – No light. I_F = 100 μA